Workshop on Connectors for Electronics-Program

Thursday December 8th, 2011,
ESPACE HAMELIN 17 rue de L’Amiral Hamelin, PARIS-France

TECHNICAL COMMITTEE:
Jean-Luc DIOT NOVAPACK Chairman
Gilles RIZZO FCI Chairman
Yves OUSTEN Laboratoire IMS
Philippe PONS AIRBUS
Yves STRICOT FCI

9.00 am Welcome
9.15 am Key Note:
European electronics industry outlook: New opportunities in a moving world
B. Dauger, DECISION

Session 1: Innovation & Performance

10.00 am New interconnection technology for wide-band microwave devices
S. Denis, P. Rethier, D. Leduc, G. Haquet, A. Girard, G. Peyresourdes,
THALES Microelectronics

10.25 am The most advanced technology for Ethernet connection ARJ45® Category 7A
X. Thomas, BEL STEWART

10.55 am-11.15 am Break

11.10 am New high density spring probe interconnection technology: miniaturisation and high reliability
J.S Lefriex, P. Reitho, HYPERTAC

11.35 am Molded interconnected devices (MID) applied to microwave components
J. Sautel, RADALL

12.00 pm-1.30 pm Lunch

Session 2: Reliability & Characterization

1.40 pm Solderless compression technology Cin: Apse and expanded beam fiber optic technology Hyperion
FQUIS -Fuel Quantity Indicating Systems, Micro D (Dura-Con™)
K. Goodwin, P. Connelly, E. Tomassi, CINCH Europe

2.05 pm DC up to 50 GHz shielded interconnection for surface mount package
B. Haentjens, VECTRAWAVE

2.30 pm-2.50 pm Break

Session 3: New Trends

2.50 pm Challenges in today’s interconnect requirements
T. Goossens, FCI

3.15 pm Impact of European directives and of environmental changes on connectors used in aeronautics
E. Scanff, C. Munier, EADS IV